# Junha Lee

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## **EDUCATION**

POSTECH

Pohang, Republic of Korea

Ph.D. in Computer Science and Engineering.

Sep. 2021 - Present

- Supervised by Prof. Jaesik Park in the Computer Vision Lab.
- Research Interest: 3D Geometry and Perception, 3D reconstruction, and Implicit representation.

**POSTECH** 

Pohang, Republic of Korea

 $Sep. \ 2019 - Aug. \ 2021$ 

M.S. in Computer Science and Engineering.

Sep. 2019 – Aug. 2021

• Master's thesis: Global Point Cloud Registration using High-dimensional ConvNets and Hough Voting (Advisor: Prof. Jaesik Park)

POSTECH

Pohang, Republic of Korea

B.E. in Computer Science and Engineering.

March. 2012 - Aug. 2019

## Publication

### International

- [1] **Junha Lee**, Christopher Choy, Animashree Anandkumar, and Jaesik Park *Putting 3D Spatially Sparse Networks on a Diet* 2112.01316 (arXiv), 2021
- [2] **Junha Lee**, Seungwook Kim, Minsu Cho, and Jaesik Park Deep Hough Voting for Robust Global Registration International Conference on Computer Vision (**ICCV**), 2021
- [3] Christopher Choy, **Junha Lee**, Rene Ranftl, Jaesik Park, and Vladlen Koltun *High-Dimensional Conovlutional Networks for Geometric Pattern Recognition* Conference on Computer Vision and Pattern Recognition (**CVPR**), 2020 (**Oral** Presentation, 5.7% acceptance rate)

### Domestic

[1] Junha Lee, Seungwook Kim, Minsu Cho, and Jaesik Park
Robust Global Registration via Hierarchical Hough Voting
33rd Workshop on Image Processing and Image Understanding (IPIU), 2021
(Gold Prize at IPIU Best Paper Award)

### Projects

### Open3D | Core Contributor

Aug 2020 – Present

- Implemented the highly optimized built-in implementations that support various neighbor search methods (Knn, Radius, and Hybrid) supporting both CPU and GPU, arbitrary data type (Float32, Float64), and index type (Int32, Int64) via a common interface.
- 6.4k Github stars

#### Professional Services

Reviewer, in CVPR (2022), ECCV(2022), ICCV (2021), BMVC (2021), IEEE RA-L/ICRA (2021)

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